



Technology

Technology	Description
Controlled Impedance	Advanced impedance tracking, measurement and modelling for multiple track shapes, lengths and materials
Planar Technology	Advanced PCB construction methods for improved conductivity, typically used with multi-layer circuits
High Voltage	Final stage HiPot stress testing methods for insulation and/or dielectric properties to ensure product longevity according to specifications
High Speed	Finer tolerances, low-loss materials and trace impedance control enable production of high-speed boards
Blind Vias	Drilled holes within a multilayer PCB connecting the outer layer to one or more inner layers
Buried Vias	Drilled holes within a multilayer PCB connecting inner layers
Copper-Filled Vias	Drilled holes within a multilayer PCB connecting the outer layer to one or more inner layers, filled with copper for enhanced conductivity *
Resin-Filled Vias	Drilled holes within a multilayer PCB connecting the outer layer to one or more inner layers, filled with resin for enhanced insulation and stability
Resin-Filled Buried Vias	Drilled holes within a multilayer PCB connecting inner layers, filled with resin for enhanced insulation and stability
Resin-Filled Blind Vias	Drilled holes within a multilayer PCB connecting inner layers to an outer layer, filled with resin for enhanced insulation and stability
Plugged Vias	Drilled holes within a multilayer PCB filled with solder mask or non-conductive ink, with no surface finish on the via barrel
Capped Vias	Any resin-filled via capped with copper to prevent chemistry/solder entering the via
Coefficient of Thermal Expansion (CTE)	Testing method employed to prevent material expansion mismatch, circuit failure and/or delamination
Thermal Management	A range of boards and materials are assessed at design stage to ensure suitable board production for heat-intensive applications
Metal Backed Substrates	Metal-backed boards with improved heat dissipation for specific applications, eg. High-powered LED's

* Available from offshore partners